ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of Invention

HIGH PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER

Application Number: 10/680783

Confirmation Number: 5859

First Named Applicant: William Jones

Attorney Docket Number:

Art Unit: Examiner:

Search string: (4145161 or 5252041 or 5259731 or 5540554 or 5865602 or 5971714 or 6041817

or 6045331 or 6123510 or 6363292 or 6616414 or 6815922 or 6966967 or

20030161734 or 20040213676 or 20050026547 or 20050111987 or 20050141998

or 20050158178 or 20050191184 or 20060130966).pn

<u>Certification:</u> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4145161	1979-03-20	Skinner			
	2	5252041	1993-10-12	Schumack			
	3	5259731	1993-11-09	Dhindsa et al.			
	4	5540554	1996-07-30	Masuzawa			
	5	5865602	1999-02-02	Nozari			
	6	5971714	1999-10-26	Schaffer et al.			
	7	6041817	2000-03-28	Guertin			
	8	6045331	2000-04-04	Gehm et al.			
	9	6123510	2000-09-26	Greer et al.			
	10	6363292	2002-03-26	McLoughlin	B1		
	11	6616414	2003-09-09	Yoo et al.	B2		
	12	6815922	2004-11-09	Yoo et al.	B2		
	13	6966967	2005-11-22	Curry et al.	B2		

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030161734	2003-08-28	Kim	A1		
	2	20040213676	2004-10-28	Phillips et al.	A1		
	3	20050026547	2005-02-03	Moore et al.	A1		
	4	20050111987	2005-05-26	Yoo et al.	A1		
	5	20050141998	2005-06-30	Yoo et al.	A1		
	6	20050158178	2005-07-21	Yoo et al.	A1		
	7	20050191184	2004-09-01	Vinson, JR.	A1	·	
	8	20060130966	2006-06-22	Babic et al.	A1		

Signature

Examiner Name	Date		